

Description

The 9DBL0641 / 9DBL0651 devices are 3.3V members of IDT's Full-Featured PCIe family. The 9DBL06 supports PCIe Gen1-4 Common Clocked (CC) and PCIe Separate Reference Independent Spread (SRIS) systems. It offers a choice of integrated output terminations providing direct connection to 85Ω or 100Ω transmission lines. The 9DBL06P1 can be factory programmed with a user-defined power up default SMBus configuration.

Recommended Application

PCIe Gen1-4 clock distribution for Riser Cards, Storage, Networking, JBOD, Communications, Access Points

Output Features

- 6 – 1-200 MHz Low-Power (LP) HCSL DIF pairs
- 9DBL0641 default Z_{OUT} = 100Ω
- 9DBL0651 default Z_{OUT} = 85Ω
- 9DBL06P1 factory programmable defaults

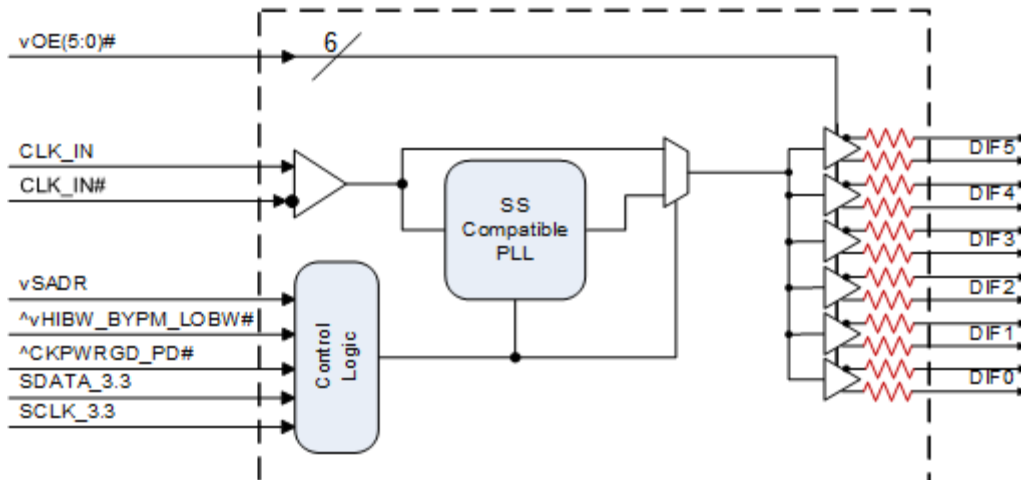
Key Specifications

- PCIe Gen1-2-3-4 CC compliant in ZDB mode
- PCIe Gen2 SRIS compliant in ZDB mode
- Supports PCIe Gen2-3 SRIS in fan-out mode
- DIF cycle-to-cycle jitter <50ps
- DIF output-to-output skew < 50ps
- Bypass mode additive phase jitter is 0 ps typical rms for PCIe
- Bypass mode additive phase jitter 160fs rms typ. @ 156.25M (1.5M to 10M)

Features/Benefits

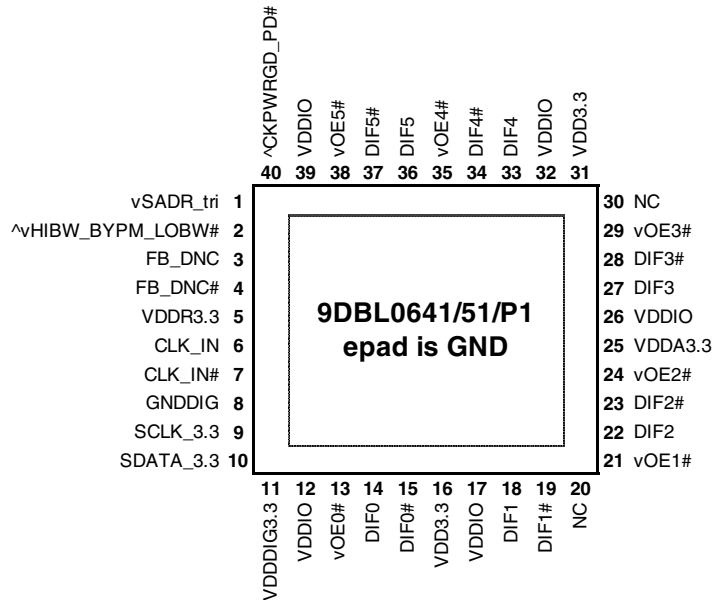
- Direct connection to 100Ω (xx41) or 85Ω (xx51) transmission lines; saves 24 resistors compared to standard PCIe devices
- 149mW typical power consumption (PLL mode@3.3V); eliminates thermal concerns
- VDDIO allows 30% power savings at optional 1.05V; maximum power savings
- SMBus-selectable features allows optimization to customer requirements:
 - control input polarity
 - control input pull up/downs
 - slew rate for each output
 - differential output amplitude
 - output impedance for each output
 - 50, 100, 125MHz operating frequency
- Customer defined SMBus power up default can be programmed into P1 device; allows exact optimization to customer requirements
- OE# pins; support DIF power management
- HCSL-compatible differential input; can be driven by common clock sources
- Spread Spectrum tolerant; allows reduction of EMI
- Pin/SMBus selectable PLL bandwidth and PLL Bypass; minimize phase jitter for each application
- Outputs blocked until PLL is locked; clean system start-up
- Device contains default configuration; SMBus interface not required for device operation
- Three selectable SMBus addresses; multiple devices can easily share an SMBus segment
- Space saving 40-pin 5x5mm VFQFPN; minimal board space

Block Diagram



Note: Default resistors are internal on xx41/xx51 devices. P1 devices have programmable default impedances on an output-by-output basis.

Pin Configuration



40-VFQFPN, 5mm x 5mm 0.4mm pin pitch

^ prefix indicates internal 120KOhm pull up resistor

^v prefix indicates internal 120KOhm pull up AND pull down resistor (biased to VDD/2)

v prefix indicates internal 120KOhm pull down resistor

SMBus Address Selection Table

| | SADR | Address | + Read/Write bit |
|---|------|---------|------------------|
| State of SADR on first application of CKPWRGD_PD# | 0 | 1101011 | x |
| | M | 1101100 | x |
| | 1 | 1101101 | x |

Note: If not using CKPWRGD (CKPWRGD tied to VDD3.3), all 3.3V VDD need to transition from 2.1V to 3.135V in <300usec.

Power Management Table

| CKPWRGD_PD# | CLK_IN | SMBus OEx bit | OEx# Pin | DIFx | | PLL |
|-------------|---------|---------------|----------|------------------|------------------|-----------------|
| | | | | True O/P | Comp. O/P | |
| 0 | X | X | X | Low ¹ | Low ¹ | Off |
| 1 | Running | 0 | X | Low ¹ | Low ¹ | On ² |
| 1 | Running | 1 | 0 | Running | Running | On ² |
| 1 | Running | 1 | 1 | Low ¹ | Low ¹ | On ² |

1. The output state is set by B11[1:0] (Low/Low default)

2. If Bypass mode is selected, the PLL will be off, and outputs will be running.

Power Connections

| Pin Number | | | Description |
|------------|--------------------|-----|-----------------------|
| VDD | VDDIO | GND | |
| 5 | | 41 | Input receiver analog |
| 11 | | 8 | Digital Power |
| 16, 31 | 12, 17, 26, 32, 39 | 41 | DIF outputs, Logic |
| 25 | | 41 | PLL Analog |

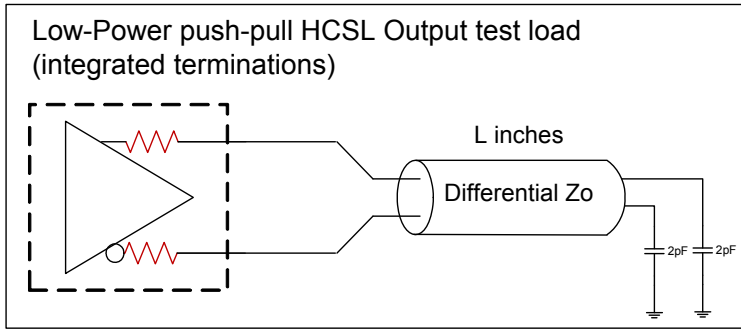
PLL Operating Mode

| HiBW_Bypm_LoBW# | MODE | Byte1 [7:6] Readback | Byte1 [4:3] Control |
|-----------------|-----------|----------------------|---------------------|
| 0 | PLL Lo BW | 00 | 00 |
| M | Bypass | 01 | 01 |
| 1 | PLL Hi BW | 11 | 11 |

Pin Descriptions

| PIN # | PIN NAME | PIN TYPE | DESCRIPTION |
|-------|-------------------|------------|---|
| 1 | vSADR_tri | LATCHED IN | Tri-level latch to select SMBus Address. See SMBus Address Selection Table. |
| 2 | ^vHIBW_BYPM_LOBW# | LATCHED IN | Trilevel input to select High BW, Bypass or Low BW mode. This pin is biased to VDD/2 (Bypass mode) with internal pull up/pull down resistors. See PLL Operating Mode Table for Details. |
| 3 | FB_DNC | DNC | True clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin. |
| 4 | FB_DNC# | DNC | Complement clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin. |
| 5 | VDDR3.3 | PWR | 3.3V power for differential input clock (receiver). This VDD should be treated as an Analog power rail and filtered appropriately. |
| 6 | CLK_IN | IN | True Input for differential reference clock. |
| 7 | CLK_IN# | IN | Complementary Input for differential reference clock. |
| 8 | GNDDIG | GND | Ground pin for digital circuitry |
| 9 | SCLK_3.3 | IN | Clock pin of SMBus circuitry, 3.3V tolerant. |
| 10 | SDATA_3.3 | I/O | Data pin for SMBus circuitry, 3.3V tolerant. |
| 11 | VDDDIG3.3 | PWR | 3.3V digital power (dirty power) |
| 12 | VDDIO | PWR | Power supply for differential outputs |
| 13 | vOE0# | IN | Active low input for enabling DIF pair 0. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 14 | DIF0 | OUT | Differential true clock output |
| 15 | DIF0# | OUT | Differential Complementary clock output |
| 16 | VDD3.3 | PWR | Power supply, nominal 3.3V |
| 17 | VDDIO | PWR | Power supply for differential outputs |
| 18 | DIF1 | OUT | Differential true clock output |
| 19 | DIF1# | OUT | Differential Complementary clock output |
| 20 | NC | N/A | No Connection. |
| 21 | vOE1# | IN | Active low input for enabling DIF pair 1. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 22 | DIF2 | OUT | Differential true clock output |
| 23 | DIF2# | OUT | Differential Complementary clock output |
| 24 | vOE2# | IN | Active low input for enabling DIF pair 2. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 25 | VDDA3.3 | PWR | 3.3V power for the PLL core. |
| 26 | VDDIO | PWR | Power supply for differential outputs |
| 27 | DIF3 | OUT | Differential true clock output |
| 28 | DIF3# | OUT | Differential Complementary clock output |
| 29 | vOE3# | IN | Active low input for enabling DIF pair 3. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 30 | NC | N/A | No Connection. |
| 31 | VDD3.3 | PWR | Power supply, nominal 3.3V |
| 32 | VDDIO | PWR | Power supply for differential outputs |
| 33 | DIF4 | OUT | Differential true clock output |
| 34 | DIF4# | OUT | Differential Complementary clock output |
| 35 | vOE4# | IN | Active low input for enabling DIF pair 4. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 36 | DIF5 | OUT | Differential true clock output |
| 37 | DIF5# | OUT | Differential Complementary clock output |
| 38 | vOE5# | IN | Active low input for enabling DIF pair 5. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs |
| 39 | VDDIO | PWR | Power supply for differential outputs |
| 40 | ^CKPWRGD_PD# | IN | Input notifies device to sample latched inputs and start up on first high assertion. Low enters Power Down Mode, subsequent high assertions exit Power Down Mode. This pin has internal pull-up resistor. |
| 41 | ePAD | GND | Connect paddle to ground. |

Test Loads



L = 5 inches

Terminations

| Device | Z_o (Ω) | R_s (Ω) |
|----------|--------------------|--------------------|
| 9DBL0641 | 100 | None needed |
| 9DBL0651 | 100 | 7.5 |
| 9DBL06P1 | 100 | Prog. |
| 9DBL0641 | 85 | N/A |
| 9DBL0651 | 85 | None needed |
| 9DBL06P1 | 85 | Prog. |

Alternate Terminations

The 9DBL0641 / 9DBL0651 can easily drive LVPECL, LVDS, and CML logic. See [“AN-891 Driving LVPECL, LVDS, and CML Logic with IDT's "Universal" Low-Power HCSL Outputs”](#) for details.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBL0641 / 9DBL0651. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|---------------------------|--------------------|---------------------------|------|-----|----------------------|-------|-------|
| Supply Voltage | VDDx | | | | 4.6 | V | 1,2 |
| Input Voltage | V _{IN} | | -0.5 | | V _{DD} +0.5 | V | 1,3 |
| Input High Voltage, SMBus | V _{IHSMB} | SMBus clock and data pins | | | 3.9 | V | 1 |
| Storage Temperature | T _s | | -65 | | 150 | °C | 1 |
| Junction Temperature | T _j | | | | 125 | °C | 1 |
| Input ESD protection | ESD prot | Human Body Model | 2500 | | | V | 1 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Operation under these conditions is neither implied nor guaranteed.

³Not to exceed 4.6V.

Electrical Characteristics–Clock Input Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|----------------------------------|--------------------|---|-----|-----|-----|-------|-------|
| Input Crossover Voltage - DIF_IN | V _{CROSS} | Cross Over Voltage | 150 | | 900 | mV | 1 |
| Input Swing - DIF_IN | V _{SWING} | Differential value | 300 | | | mV | 1 |
| Input Slew Rate - DIF_IN | dv/dt | Measured differentially | 0.4 | | 8 | V/ns | 1,2 |
| Input Leakage Current | I _{IN} | V _{IN} = V _{DD} , V _{IN} = GND | -5 | | 5 | uA | |
| Input Duty Cycle | d _{tin} | Measurement from differential waveform | 45 | | 55 | % | 1 |
| Input Jitter - Cycle to Cycle | J _{DIFIn} | Differential Measurement | 0 | | 125 | ps | 1 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics–SMBus Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|---------------------------|---------------------|--------------------------------------|-----|-----|------|-------|-------|
| SMBus Input Low Voltage | V _{ILSMB} | V _{DDSMB} = 3.3V | | | 0.8 | V | |
| SMBus Input High Voltage | V _{IHSMB} | V _{DDSMB} = 3.3V | 2.1 | | 3.6 | V | |
| SMBus Output Low Voltage | V _{OLSMB} | @ I _{PULLUP} | | | 0.4 | V | |
| SMBus Sink Current | I _{PULLUP} | @ V _{OL} | 4 | | | mA | |
| Nominal Bus Voltage | V _{DDSMB} | | 2.7 | | 3.6 | V | |
| SCLK/SDATA Rise Time | t _{RSMB} | (Max VIL - 0.15) to (Min VIH + 0.15) | | | 1000 | ns | 1 |
| SCLK/SDATA Fall Time | t _{FSMB} | (Min VIH + 0.15) to (Max VIL - 0.15) | | | 300 | ns | 1 |
| SMBus Operating Frequency | f _{SMB} | SMBus operating frequency | | | 500 | kHz | 2,3 |

¹Guaranteed by design and characterization, not 100% tested in production.

²The device must be powered up for the SMBus to function.

³The differential input clock must be running for the SMBus to be active

Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|--|------------------------|---|-----------------------|----------------------|------------------------|--------|-------|
| Supply Voltage | V _{DDx} | Supply voltage for core and analog | 3.135 | 3.3 | 3.465 | V | |
| Output Supply Voltage | V _{DDIO} | Supply voltage for Low Power HCSL Outputs | 0.95 | 1.05-3.3 | 3.465 | V | |
| Ambient Operating Temperature | T _{AMB} | Industrial range | -40 | 25 | 85 | °C | |
| Input High Voltage | V _{IH} | Single-ended inputs, except SMBus | 0.75 V _{DDx} | | V _{DDx} + 0.3 | V | |
| Input Low Voltage | V _{IL} | | -0.3 | | 0.25 V _{DDx} | V | |
| Input High Voltage | V _{IHtri} | Single-ended tri-level inputs ('_tri' suffix) | 0.75 V _{DDx} | | V _{DD} + 0.3 | V | |
| Input Mid Voltage | V _{IMtri} | | 0.4 V _{DDx} | 0.5 V _{DDx} | 0.6 V _{DDx} | V | |
| Input Low Voltage | V _{ILtri} | | -0.3 | | 0.25 V _{DDx} | V | |
| Input Current | I _{IN} | Single-ended inputs, V _{IN} = GND, V _{IN} = VDD | -5 | | 5 | uA | |
| | I _{INP} | Single-ended inputs V _{IN} = 0 V; Inputs with internal pull-up resistors V _{IN} = VDD; Inputs with internal pull-down resistors | -50 | | 50 | uA | |
| Input Frequency | F _{IN} | Bypass mode | 1 | | 200 | MHz | 2 |
| | | 100MHz PLL mode | 60 | 100.00 | 140 | MHz | 2 |
| | | 50MHz PLL mode | 30 | 50.00 | 65 | MHz | 2 |
| | | 125MHz PLL mode | 75 | 125.00 | 175 | MHz | 2 |
| Pin Inductance | L _{pin} | | | 7 | nH | 1 | |
| Capacitance | C _{IN} | Logic Inputs, except DIF_IN | 1.5 | | 5 | pF | 1 |
| | C _{INDIF_IN} | DIF_IN differential clock inputs | 1.5 | | 2.7 | pF | 1 |
| | C _{OUT} | Output pin capacitance | | | 6 | pF | 1 |
| Clk Stabilization | T _{STAB} | From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock | | | 1 | ms | 1,2 |
| Input SS Modulation Frequency PCIe | f _{MODINPCIe} | Allowable Frequency for PCIe Applications (Triangular Modulation) | 30 | | 33 | kHz | |
| Input SS Modulation Frequency non-PCIe | f _{MODIN} | Allowable Frequency for non-PCIe Applications (Triangular Modulation) | 0 | | 66 | kHz | |
| OE# Latency | t _{LATOE#} | DIF start after OE# assertion DIF stop after OE# deassertion | 1 | | 3 | clocks | 1,3 |
| Tdrive_PD# | t _{DRVPD} | DIF output enable after PD# de-assertion | | | 300 | us | 1,3 |
| Tfall | t _F | Fall time of single-ended control inputs | | | 5 | ns | 2 |
| Trise | t _R | Rise time of single-ended control inputs | | | 5 | ns | 2 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

Electrical Characteristics–DIF Low-Power HCSL Outputs

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|------------------------------|---|------|-----|------|-------|-------|
| Slew rate | dV/dt | Scope averaging on, fast setting | 2 | 2.8 | 4 | V/ns | 1,2,3 |
| | dV/dt | Scope averaging on, slow setting | 1.2 | 1.9 | 3.1 | V/ns | 1,2,3 |
| Slew rate matching | Δ dV/dt | Slew rate matching | | 7 | 20 | % | 1,2,4 |
| Voltage High | V _{HIGH} | Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on) | 660 | 768 | 850 | mV | 7 |
| Voltage Low | V _{LOW} | | -150 | -11 | 150 | | 7 |
| Max Voltage | V _{max} | Measurement on single ended signal using absolute value. (Scope averaging off) | | 811 | 1150 | mV | 7 |
| Min Voltage | V _{min} | | -300 | -49 | | | 7 |
| Crossing Voltage (abs) | V _{cross_abs} | Scope averaging off | 250 | 357 | 550 | mV | 1,5 |
| Crossing Voltage (var) | Δ -V _{cross} | Scope averaging off | | 14 | 140 | mV | 1,6 |

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the V_{swing} voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of V_{cross_min/max} (V_{cross} absolute) allowed. The intent is to limit V_{cross} induced modulation by setting Δ -V_{cross} to be smaller than V_{cross} absolute.

⁷ At default SMBus settings.

Electrical Characteristics–Current Consumption

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|--------------------------|---------------------|-----------------------------------|-----|------|------|-------|-------|
| Operating Supply Current | I _{DDA} | VDDA, PLL Mode, @100MHz | | 7 | 15 | mA | |
| | I _{DD} | VDDx, All outputs active @100MHz | | 17 | 22 | mA | |
| | I _{DDIO} | VDDIO, All outputs active @100MHz | | 20 | 25 | mA | |
| Powerdown Current | I _{DDAPD} | VDDA, CKPWRGD_PD#=0 | | 0.6 | 2 | mA | 2 |
| | I _{DDPD} | VDDx, CKPWRGD_PD#=0 | | 3.8 | 6 | mA | 2 |
| | I _{DDIOPD} | VDDIO, CKPWRGD_PD#=0 | | 0.04 | 0.10 | mA | 2 |

¹ Guaranteed by design and characterization, not 100% tested in production.

² Input clock stopped.

Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|----------------------|--------------------------------------|------|------|------|-------|-------|
| PLL Bandwidth | BW | -3dB point in High BW Mode (100MHz) | 2 | 3.3 | 4 | MHz | 1,5 |
| | | -3dB point in Low BW Mode (100MHz) | 1 | 1.5 | 2 | MHz | 1,5 |
| PLL Jitter Peaking | t _{JPEAK} | Peak Pass band Gain (100MHz) | | 0.8 | 2 | dB | 1 |
| Duty Cycle | t _{DC} | Measured differentially, PLL Mode | 45 | 50 | 55 | % | 1 |
| Duty Cycle Distortion | t _{DCD} | Measured differentially, Bypass Mode | -1 | 0.0 | 1 | % | 1,3 |
| Skew, Input to Output | t _{pdBYP} | Bypass Mode, V _T = 50% | 2500 | 3406 | 4500 | ps | 1 |
| | t _{pdPLL} | PLL Mode V _T = 50% | -100 | 8 | 100 | ps | 1,4 |
| Skew, Output to Output | t _{sk3} | V _T = 50% | | 21 | 55 | ps | 1,4 |
| | | PLL mode | | 15 | 50 | ps | 1,2 |
| Jitter, Cycle to cycle | t _{jcy-cyc} | Additive Jitter in Bypass Mode | | 0.1 | 1 | ps | 1,2 |

¹ Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

⁴ All outputs at default slew rate

⁵ The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

Electrical Characteristics–Filtered Phase Jitter Parameters - PCIe Common Clocked (CC) Architectures

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|---------------------------|---|-----|-----|------|----------------|----------|---------|
| Phase Jitter, PLL Mode | t _{jphPCIeG1-CC} | PCIe Gen 1 | | 23 | 32 | 86 | ps (p-p) | 1,2,3,5 |
| | t _{jphPCIeG2-CC} | PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.6 | 0.8 | 3 | ps (rms) | 1,2,5 |
| | | PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 1.7 | 2.1 | 3.1 | ps (rms) | 1,2,5 |
| | t _{jphPCIeG3-CC} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.4 | 0.48 | 1 | ps (rms) | 1,2,5 |
| | t _{jphPCIeG4-CC} | PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.4 | 0.48 | 0.5 | ps (rms) | 1,2,5 |
| Additive Phase Jitter, Bypass mode | t _{jphPCIeG1-CC} | PCIe Gen 1 | | 0.0 | 0.01 | n/a | ps (p-p) | 1,2,5 |
| | t _{jphPCIeG2-CC} | PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | | PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | t _{jphPCIeG3-CC} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | t _{jphPCIeG4-CC} | PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |

¹ Applies to all outputs.

² Based on PCIe Base Specification Rev4.0 version 0.7draft. See <http://www.pcisig.com> for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values additive jitter is calculated by solving the following equation for b [$a^2 + b^2 = c^2$] where a is rms input jitter and c is rms total jitter.

⁵ Driven by 9FGL0841 or equivalent

Electrical Characteristics–Filtered Phase Jitter Parameters - PCIe Separate Reference Independent Spread (SRIS) Architectures⁵

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|-----------------------------|---|-----|-----|------|----------------|----------|---------|
| Phase Jitter, PLL Mode | t _{jphPCIeG2-SRIS} | PCIe Gen 2 (PLL BW of 16MHz , CDR = 5MHz) | | 1.2 | 1.5 | 2 | ps (rms) | 1,2 |
| | t _{jphPCIeG3-SRIS} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | n/a | | 0.5 | ps (rms) | 1,2,6 |
| Additive Phase Jitter, Bypass mode | t _{jphPCIeG2-SRIS} | PCIe Gen 2 (PLL BW of 16MHz , CDR = 5MHz) | | 0.0 | 0.01 | n/a | ps (rms) | 1,2,4 |
| | t _{jphPCIeG3-SRIS} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,6 |

¹ Applies to all outputs.

² Based on PCIe Base Specification Rev3.1a. These filters are different than Common Clock filters. See <http://www.pcisig.com> for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values, additive jitter is calculated by solving the following equation for b [$a^2+b^2=c^2$] where a is rms input jitter and c is rms total jitter.

⁵ As of PCIe Base Specification Rev4.0 draft 0.7, SRIS is not currently defined for Gen1 or Gen4.

⁶ This device does not support PCIe Gen3 SRIS in PLL mode. It supports PCIe Gen3 SRIS in bypass mode.

Electrical Characteristics– Unfiltered Phase Jitter Parameters

T_A = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|----------------------------|--|-----|-----|-----|----------------|----------|-------|
| Additive Phase Jitter, Fanout Mode | t _{jph156M} | 156.25MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz | | 159 | | N/A | fs (rms) | 1,2,3 |
| | t _{jph156M12k-20} | 156.25MHz, 12kHz to 20MHz, -20dB/decade rollover < 12kHz, -40db/decade rolloff > 20MHz | | 363 | | N/A | fs (rms) | 1,2,3 |

¹ Guaranteed by design and characterization, not 100% tested in production.

² DRiven by Rohde&Schartz SMA100

³ For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)² - (input jitter)²]

General SMBus Serial Interface Information

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

| Index Block Write Operation | | | |
|-----------------------------|-----------|--------|----------------------|
| Controller (Host) | | | IDT (Slave/Receiver) |
| T | starT bit | | |
| Slave Address | | | |
| WR | WRite | | |
| | | | ACK |
| Beginning Byte = N | | | |
| | | | ACK |
| Data Byte Count = X | | | |
| | | | ACK |
| Beginning Byte N | | X Byte | |
| O | | | ACK |
| O | | | O |
| O | | | O |
| | | | O |
| Byte N + X - 1 | | | |
| | | | ACK |
| P | stoP bit | | |

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

| Index Block Read Operation | | | |
|----------------------------|-----------------|--------|----------------------|
| Controller (Host) | | | IDT (Slave/Receiver) |
| T | starT bit | | |
| Slave Address | | | |
| WR | WRite | | |
| | | | ACK |
| Beginning Byte = N | | | |
| | | | ACK |
| RT | Repeat starT | | |
| Slave Address | | | |
| RD | ReaD | | |
| | | | ACK |
| | | | Data Byte Count=X |
| ACK | | X Byte | |
| ACK | | | Beginning Byte N |
| | | | O |
| | | | O |
| | | | O |
| | | | Byte N + X - 1 |
| N | Not acknowledge | | |
| P | stoP bit | | |

Note: SMBus Address is Latched on SADR pin.
Unless otherwise indicated, default values are for the 641 and 0651. P1 devices are fully factory programmable.

SMBus Table: Output Enable Register ¹

| Byte 0 | Name | Control Function | Type | 0 | 1 | Default |
|--------|----------|------------------|------|--------------|-------------|---------|
| Bit 7 | DIF OE5 | Output Enable | RW | See B11[1:0] | Pin Control | 1 |
| Bit 6 | DIF OE4 | Output Enable | RW | | Pin Control | 1 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | DIF OE3 | Output Enable | RW | See B11[1:0] | Pin Control | 1 |
| Bit 3 | DIF OE2 | Output Enable | RW | | Pin Control | 1 |
| Bit 2 | DIF OE1 | Output Enable | RW | | Pin Control | 1 |
| Bit 1 | Reserved | | | | | 0 |
| Bit 0 | DIF OE0 | Output Enable | RW | See B11[1:0] | Pin Control | 1 |

1. A low on these bits will override the OE# pin and force the differential output to the state indicated by B11[1:0] (Low/Low default)

SMBus Table: PLL Operating Mode and Output Amplitude Control Register

| Byte 1 | Name | Control Function | Type | 0 | 1 | Default |
|--------|-----------------|-------------------------------|-----------------|--------------------------------|--------------------------------|---------|
| Bit 7 | PLLMODERB1 | PLL Mode Readback Bit 1 | R | See PLL Operating Mode Table | | Latch |
| Bit 6 | PLLMODERB0 | PLL Mode Readback Bit 0 | R | | | Latch |
| Bit 5 | PLLMODE_SWCNTRL | Enable SW control of PLL Mode | RW | Values in B1[7:6] set PLL Mode | Values in B1[4:3] set PLL Mode | 0 |
| Bit 4 | PLLMODE1 | PLL Mode Control Bit 1 | RW ¹ | See PLL Operating Mode Table | | 0 |
| Bit 3 | PLLMODE0 | PLL Mode Control Bit 0 | RW ¹ | | | 0 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | AMPLITUDE 1 | Controls Output Amplitude | RW | 00 = 0.6V | 01 = 0.68V | 1 |
| Bit 0 | AMPLITUDE 0 | | RW | 10 = 0.75V | 11 = 0.85V | 0 |

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

SMBus Table: Slew Rate Control Register

| Byte 2 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------------------|---------------------|------|--------------|--------------|---------|
| Bit 7 | SLEWRATESEL DIF5 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 6 | SLEWRATESEL DIF4 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 5 | Reserved | | | | | 1 |
| Bit 4 | SLEWRATESEL DIF3 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 3 | SLEWRATESEL DIF2 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 2 | SLEWRATESEL DIF1 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 1 | Reserved | | | | | 1 |
| Bit 0 | SLEWRATESEL DIF0 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |

Note: See "Low-Power HCSL Outputs" table for slew rates.

SMBus Table: Slew Rate Control Register

| Byte 3 | Name | Control Function | Type | 0 | 1 | Default |
|--------|----------------|----------------------------------|-----------------|---|-----------------------------|---------|
| Bit 7 | Reserved | | | | | 1 |
| Bit 6 | Reserved | | | | | 1 |
| Bit 5 | FREQ_SEL_EN | Enable SW selection of frequency | RW | SW frequency change disabled | SW frequency change enabled | 0 |
| Bit 4 | FSEL1 | Freq. Select Bit 1 | RW ¹ | 00 = 100M, 10 = 125M 01 = 50M, 11 = Reserved | | 0 |
| Bit 3 | FSEL0 | Freq. Select Bit 0 | RW ¹ | | | 0 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | Reserved | | | | | 1 |
| Bit 0 | SLEWRATESEL FB | Adjust Slew Rate of FB | RW | Slow Setting | Fast Setting | 1 |

1. B3[5] must be set to a 1 for these bits to have any effect on the part.

Byte 4 is Reserved

SMBus Table: Revision and Vendor ID Register

| Byte 5 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------|------------------|------|--------------|---|---------|
| Bit 7 | RID3 | Revision ID | R | B rev = 0001 | | 0 |
| Bit 6 | RID2 | | R | | | 0 |
| Bit 5 | RID1 | | R | | | 0 |
| Bit 4 | RID0 | | R | | | 1 |
| Bit 3 | VID3 | VENDOR ID | R | 0001 = IDT | | 0 |
| Bit 2 | VID2 | | R | | | 0 |
| Bit 1 | VID1 | | R | | | 0 |
| Bit 0 | VID0 | | R | | | 1 |

SMBus Table: Device Type/Device ID

| Byte 6 | Name | Control Function | Type | 0 | 1 | Default |
|--------|--------------|------------------|------|--|---|---------|
| Bit 7 | Device Type1 | Device Type | RW | 00 = FGx, 01 = DBx ZDB/FOB, 10 = DMx, 11= DBx FOB | | 0 |
| Bit 6 | Device Type0 | | RW | | | 1 |
| Bit 5 | Device ID5 | Device ID | RW | 000110binary or 06 hex | | 0 |
| Bit 4 | Device ID4 | | RW | | | 0 |
| Bit 3 | Device ID3 | | RW | | | 0 |
| Bit 2 | Device ID2 | | RW | | | 1 |
| Bit 1 | Device ID1 | | RW | | | 1 |
| Bit 0 | Device ID0 | | RW | | | 0 |

SMBus Table: Byte Count Register

| Byte 7 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------|------------------------|------|---|---|---------|
| Bit 7 | | Reserved | | | | 0 |
| Bit 6 | | Reserved | | | | 0 |
| Bit 5 | | Reserved | | | | 0 |
| Bit 4 | BC4 | Byte Count Programming | RW | Writing to this register will configure how many bytes will be read back, default is = 8 bytes. | | 0 |
| Bit 3 | BC3 | | RW | | | 1 |
| Bit 2 | BC2 | | RW | | | 0 |
| Bit 1 | BC1 | | RW | | | 0 |
| Bit 0 | BC0 | | RW | | | 0 |

Bytes 8 and 9 are Reserved

SMBus Table: PD_Restore

| Byte 10 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------------------|-------------------------------|------|--------------------|-------------------|---------|
| Bit 7 | | Reserved | | | | 1 |
| Bit 6 | Power-Down (PD) Restore | Restore Default Config. In PD | RW | Clear Config in PD | Keep Config in PD | 1 |
| Bit 5 | | Reserved | | | | 0 |
| Bit 4 | | Reserved | | | | 0 |
| Bit 3 | | Reserved | | | | 0 |
| Bit 2 | | Reserved | | | | 0 |
| Bit 1 | | Reserved | | | | 0 |
| Bit 0 | | Reserved | | | | 0 |

SMBus Table: Stop State and Impedance Control

| Byte 11 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-----------|---|------|-----------------|------------------|----------|
| Bit 7 | FB_imp[1] | FB Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 6 | FB_imp[0] | FB Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 0 |
| Bit 3 | Reserved | | | | | 0 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | STP[1] | True/Complement DIF Output Disable State | RW | 00 = Low/Low | 10 = High/Low | 0 |
| Bit 0 | STP[0] | | RW | 01 = HiZ/HiZ | 11 = Low/High | 0 |

Note: xx41 = 10, xx51 = 01, P1 = factory programmable.

SMBus Table: Impedance Control

| Byte 12 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------|------------------|------|-----------------|------------------|----------|
| Bit 7 | DIF2_imp[1] | DIF2 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 6 | DIF2_imp[0] | DIF2 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 5 | DIF1_imp[1] | DIF1 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | |
| Bit 4 | DIF1_imp[0] | DIF1 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 3 | Reserved | | | | | X |
| Bit 2 | Reserved | | | | | X |
| Bit 1 | DIF0_imp[1] | DIF0 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 0 | DIF0_imp[0] | DIF0 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |

Note: xx41 = 10, xx51 = 01, P1 = factory programmable.

SMBus Table: Impedance Control

| Byte 13 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------|------------------|------|-----------------|------------------|----------|
| Bit 7 | DIF5_imp[1] | DIF5 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 6 | DIF5_imp[0] | DIF5 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 5 | DIF4_imp[1] | DIF4 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | |
| Bit 4 | DIF4_imp[0] | DIF6 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 3 | Reserved | | | | | X |
| Bit 2 | Reserved | | | | | X |
| Bit 1 | DIF3_imp[1] | DIF3 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 0 | DIF3_imp[0] | DIF3 Zout | RW | 01=85Ω DIF Zout | 11 = Reserved | |

Note: xx41 = 10, xx51 = 01, P1 = factory programmable.

SMBus Table: Pull-up Pull-down Control

| Byte 14 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|--|------|---------|---------------|---------|
| Bit 7 | OE2_pu/pd[1] | OE2 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 6 | OE2_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 5 | OE1_pu/pd[1] | OE1 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 4 | OE1_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 3 | Reserved | | | | | X |
| Bit 2 | Reserved | | | | | X |
| Bit 1 | OE0_pu/pd[1] | OE0 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 0 | OE0_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |

Note: These values are for xx41 and xx51. P1 is factory programmable.

SMBus Table: Pull-up Pull-down Control

| Byte 15 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|--|------|---------|---------------|---------|
| Bit 7 | OE5_pu/pd[1] | OE5 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 6 | OE5_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 5 | OE4_pu/pd[1] | OE4 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 4 | OE4_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 3 | Reserved | | | | | X |
| Bit 2 | Reserved | | | | | X |
| Bit 1 | OE3_pu/pd[1] | OE3 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 0 | OE3_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |

Note: These values are for xx41 and xx51. P1 is factory programmable.

SMBus Table: Pull-up Pull-down Control

| Byte 16 | Name | Control Function | Type | 0 | 1 | Default |
|---------|---------------------|---|------|---------|---------------|---------|
| Bit 7 | Reserved | | | | | 0 |
| Bit 6 | Reserved | | | | | 0 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 0 |
| Bit 3 | Reserved | | | | | X |
| Bit 2 | Reserved | | | | | X |
| Bit 1 | CKPWRGD_PD_pu/pd[1] | CKPWRGD_PD Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 1 |
| Bit 0 | CKPWRGD_PD_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 0 |

* 9DBL09xx devices only.

Note: These values are for xx41 and xx51. P1 is factory programmable.

Bytes 17 is Reserved and reads back 0h00.

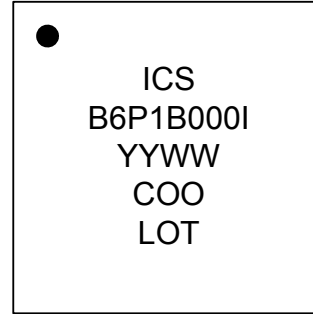
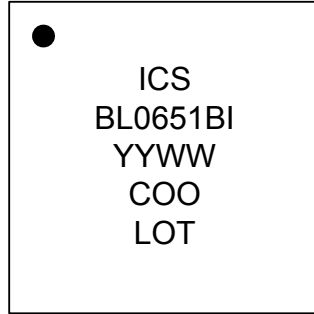
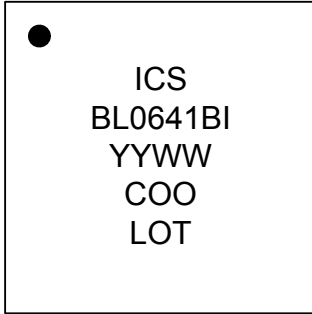
SMBus Table: Polarity Control

| Byte 18 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|-------------------|------|------------------|-------------------|---------|
| Bit 7 | OE5_polarity | Sets OE5 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 6 | OE4_polarity | Sets OE4 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | OE3_polarity | Sets OE3 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 3 | OE2_polarity | Sets OE2 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 2 | OE1_polarity | Sets OE1 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 1 | Reserved | | | | | 0 |
| Bit 0 | OE0_polarity | Sets OE0 polarity | RW | Enabled when Low | Enabled when High | 0 |

SMBus Table: Polarity Control

| Byte 19 | Name | Control Function | Type | 0 | 1 | Default |
|---------|------------|-----------------------------------|------|------------------------|-------------------------|---------|
| Bit 7 | Reserved | | | | | 0 |
| Bit 6 | Reserved | | | | | 0 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 0 |
| Bit 3 | Reserved | | | | | 0 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | Reserved | | | | | 0 |
| Bit 0 | CKPWRGD_PD | Determines CKPWRGD_PD polarity | RW | Power Down when Low | Power Down when High | 0 |

Marking Diagrams



Notes:

1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. YYWW is the last two digits of the year and week that the part was assembled.
4. Line 2: truncated part number
5. "I" denotes industrial temperature range device.

Thermal Characteristics

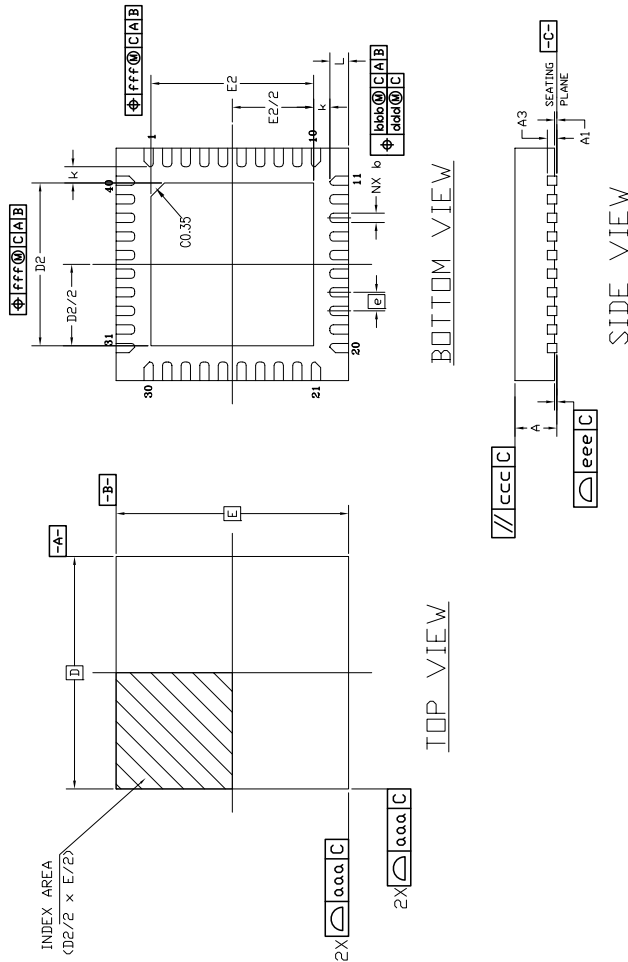
| PARAMETER | SYMBOL | CONDITIONS | PKG | TYP. VALUE | UNITS | NOTES |
|--------------------|-------------------------|---------------------------------|-------|------------|-------|-------|
| Thermal Resistance | θ_{JC} | Junction to Case | NDG40 | 42 | °C/W | 1 |
| | θ_{Jb} | Junction to Base | | 2.4 | °C/W | 1 |
| | θ_{JA0}^{θ} | Junction to Air, still air | | 39 | °C/W | 1 |
| | θ_{JA1} | Junction to Air, 1 m/s air flow | | 33 | °C/W | 1 |
| | θ_{JA3} | Junction to Air, 3 m/s air flow | | 28 | °C/W | 1 |
| | θ_{JA5} | Junction to Air, 5 m/s air flow | | 27 | °C/W | 1 |

¹ePad soldered to board

Package Outline and Dimensions (NDG40)

| REVISIONS | | | |
|-----------|-----------------|---------|----------|
| REV | DESCRIPTION | DATE | APPROVED |
| 00 | INITIAL RELEASE | 5/17/16 | JH |

| SYMBOL | DIMENSION | | |
|--------|-------------|------|------|
| | MIN | NOM | MAX |
| b | 0.15 | 0.20 | 0.25 |
| D | 5.00 BSC | | |
| E | 5.00 BSC | | |
| D2 | 3.40 | 3.50 | 3.60 |
| E2 | 3.40 | 3.50 | 3.60 |
| L | 0.30 | 0.40 | 0.50 |
| e | 0.40 BSC | | |
| N | 40 | | |
| ND | 10 (note 3) | | |
| NE | 10 (note 3) | | |
| A | 0.80 | 0.90 | 1.00 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | 0.2 REF | | |
| k | 0.35 REF | | |
| ooo | 0.10 | | |
| bbb | 0.07 | | |
| ccc | 0.10 | | |
| ddd | 0.05 | | |
| eee | 0.08 | | |
| fff | 0.10 | | |



NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.

| | |
|---|---|
| TOLERANCES UNLESS SPECIFIED DECIMAL ±1° XX±.05 XXX±.030 APPROVALS DRAWN <i>mm</i> CHECKED | 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 |
| | www.IDT.com |
| | TITLE: NDG40 PACKAGE OUTLINE 5.0 x 5.0 mm BODY, EPAD 3.50mm SQ. 0.40 mm PITCH QFN |
| | SIZE: DRAWING No. C PSC-4292-02 REV: 00 DO NOT SCALE DRAWING SHEET 1 OF 2 |

Package Outline and Dimensions, cont. (NDG40)

| REVISIONS | | | |
|-----------|-----------------|---------|----------|
| REV | DESCRIPTION | DATE | APPROVED |
| 00 | INITIAL RELEASE | 5/17/16 | JH |

RECOMMENDED LAND PATTERN

NOTES:

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. TOP DOWN VIEW AS VIEWED ON PCB.
3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

| | |
|--|--|
| 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com | |
| TOLERANCES UNLESS SPECIFIED DECIMAL ±0.1 XXX±.05 XXXX ±.030 | 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com |
| APPROVALS DRAWN <i>7/08</i> CHECKED | TITLE/NDG40 PACKAGE OUTLINE 5.0 x 5.0 mm BODY, EPAD 3.50mm SQ. 0.40 mm PITCH QFN |
| DATE 05/31/10 | SIZE DRAWING No. C PSC-4292-02 |
| DO NOT SCALE DRAWING | REV 00 SHEET 2 OF 2 |

Ordering Information

| Part / Order Number | Output Impedance | Shipping Packaging | Package | Temperature |
|---------------------|--|--------------------|---------------|---------------|
| 9DBL0641BKILF | 100Ω | Trays | 40-pin VFQFPN | -40 to +85° C |
| 9DBL0641BKILFT | | Tape and Reel | 40-pin VFQFPN | -40 to +85° C |
| 9DBL0651BKILF | 85Ω | Trays | 40-pin VFQFPN | -40 to +85° C |
| 9DBL0651BKILFT | | Tape and Reel | 40-pin VFQFPN | -40 to +85° C |
| 9DBL06P1BxxxKILF | Factory configurable. Contact IDT for additional information. | Trays | 40-pin VFQFPN | -40 to +85° C |
| 9DBL06P1BxxxKILFT | | Tape and Reel | 40-pin VFQFPN | -40 to +85° C |

“LF” suffix to the part number are the Pb-Free configuration and are RoHS compliant.

“B” is the device revision designator (will not correlate with the datasheet revision).

“xxx” is a unique factory assigned number to identify a particular default configuration.

Revision History

| Rev. | Initiator | Issue Date | Description | Page # |
|------|-----------|------------|---|---------|
| B | RDW | 6/2/2016 | 1. Electrical Table and SMBus Updates/Corrections 2. Release to final. | Various |
| C | RDW | 6/7/2016 | 1. SMBus operating frequency is now set to 500kHz max. 2. Removed duplicate Absolute Maximum Table. 3. Corrected "Test Loads" table | Various |
| D | RDW | 6/8/2016 | 1. Added Frequency Select info to Byte 3 | 11 |
| E | RDW | 6/14/2016 | 1. Updated IDD tables | 7 |
| F | RDW | 9/2/2016 | 1. Corrected Byte 2 to properly indicate slew rate control bits | 11 |
| G | RDW | 2/8/2017 | Updated part numbering throughout datasheet to be 9DBL0641 / 9DBL0651 | Various |



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С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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